

3.3V, PCI Express® 3.0 2-Lane, 2:1 Mux/DeMux Switch, with Single Enable

### **Features**

- → 4 Differential Channel, 2:1 Mux/DeMux
- → PCI Express® 3.0 Performance, 8.0Gbps
- → Bi-directional Operation
- → Low Bit-to-Bit Skew, 10ps max
- → Low channel-to-channel skew, 20ps max
- → Low Crosstalk: -35dB@4 GHz
- → High Off Isolation: -22dB@4 GHz (8.0Gbps)
- → Low insertion loss: -1.3dB@4 GHz (8.0Gbps)
- → Return loss: -21dB@4 GHz
- → ESD:1.5KV HBM
- → Support for DP1.2 HBR2, HBR, RBR
- → Supply Voltage 3.3V
- → Industrial Temperature Range: -40°C to 85°C
- → Packaging (Pb-free & Green):
  - 42-contact, TQFN (ZH42), 3.5 x 9mm
  - 40-contact, TQFN (ZL40), 3 x 6mm

### **Description**

The PI3PCIE3412A is an 8 to 4 differential channel multiplexer/demultiplexer switch. This solution can switch 2 full PCI Express® 3.0, lanes to one of two locations. Using a unique design technique, Diodes Incorporated has been able to minimize the impedance of the switch such that the attenuation observed through the switch is minimal. The unique design technique also offers a layout targeted for PCI Express signals, which minimizes the channel to channel skew as well as channel to channel crosstalk as required by the PCI Express specification.

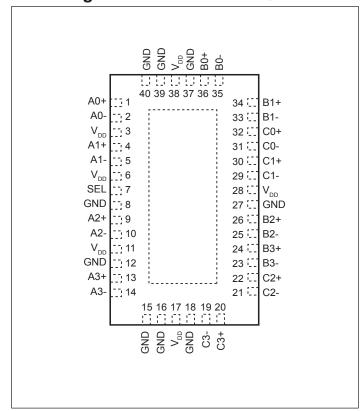
The PI3PCIE3412A can also be used for application up to 12Gbps.

### **Application**

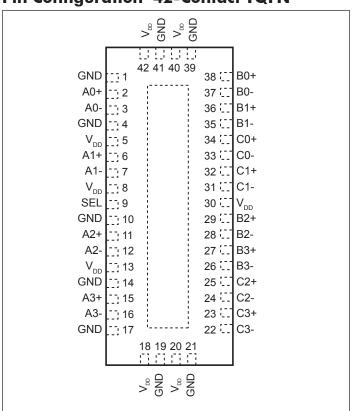
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Routing of PCI Express 3.0, DP1.2, USB3.0, SAS2.0, SATA3.0, XAUI, RXAUI signals with low signal attenuation.

## **Pin Configuration 40-Contact TQFN**



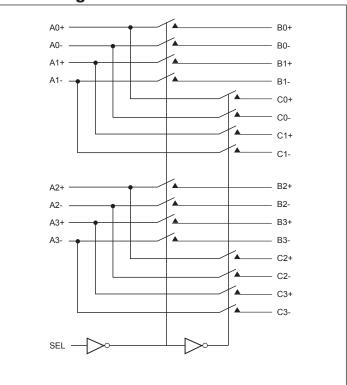
## Pin Configuration 42-Contact TQFN







## **Block Diagram**



### **Truth Table**

Function	SEL
A <sub>N</sub> to B <sub>N</sub>	L
A <sub>N</sub> to C <sub>N</sub>	Н





## **Pin Description**

Pin #						
42-TQFN	40-TQFN	Pin Name	I/O	Description		
2	1	A0+	I/O	C: INO CI IO D. 4 A		
3	2	A0-	I/O	Signal I/O, Channel 0, Port A		
6	4	A1+	I/O	Cinnal I/O Channal I Don't A		
7	5	A1-	I/O	Signal I/O, Channel 1, Port A		
11	9	A2+	I/O	Signal I/O, Channel 2, Port A		
12	10	A2-	I/O	Signal I/O, Channel 2, Port A		
15	13	A3+	I/O	Signal I/O Channel 2 Pout A		
16	14	A3-	I/O	Signal I/O, Channel 3, Port A		
38	36	B0+	I/O	Signal I/O Chammal O Dout D		
37	35	В0-	I/O	Signal I/O, Channel 0, Port B		
36	34	B1+	I/O	Signal I/O Channel 1 Pout D		
35	33	B1-	1/0	Signal I/O, Channel 1, Port B		
29	26	B2+	I/O	Signal I/O Chammal 2 Pout P		
28	25	B2-	I/O	Signal I/O, Channel 2, Port B		
27	24	B3+	I/O	Cional I/O Channel 2 Pont P		
26	23	В3-	1/0	Signal I/O, Channel 3, Port B		
34	32	C0+	I/O	Signal I/O Channel O Powt C		
33	31	C0-	1/0	Signal I/O, Channel 0, Port C		
32	30	C1+	I/O	Signal I/O, Channel 1, Port C		
31	29	C1-	1/0	Signal 1/O, Channel 1, Port C		
25	22	C2+	I/O	Signal I/O, Channel 2, Port C		
24	21	C2-	1/0	Signal 1/O, Chamie 2, Port C		
23	20	C3+	I/O	Signal I/O Channel 2 Port C		
22	19	C3-	1/0	Signal I/O, Channel 3, Port C		
9	7	SEL	I	Operation mode Select (when SEL=0: A→B, when SEL=1: A→C		
5, 8, 13,18, 20, 30, 40, 42	3, 6, 11, 17, 28, 38	$V_{\mathrm{DD}}$	Pwr	3.3V ±10% Positive Supply Voltage		
1, 4, 10, 14, 17, 19, 21, 39, 41, Center Pad	8, 12, 15, 16, 18, 27, 37, 39, 40	GND	Pwr	Power ground		





### **Maximum Ratings**

(Above which useful life may be impaired. For user guidelines, not tested.)

<u> </u>	
Storage Temperature	-65°C to +150°C
Supply Voltage to Ground Potential	0.5V to +3.7V
Channel DC Input Voltage	0.5V to 1.5V
DC Output Current	120mA
Power Dissipation	0.5W
SEL DC Input Voltage	0.5V to 3.7V
Junction Temperature	125°C

**Note:** Stresses greater than those listed under MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

### **Electrical Characteristics**

**Recommended Operating Conditions** 

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Units
$V_{\mathrm{DD}}$	3.3V Power Supply		3.0	3.3	3.6	V
I <sub>DD</sub>	Total current from V <sub>DD</sub> 3.3V supply	$SEL = 0V \text{ or } V_{DD}$		0.15	1	mA
V <sub>I/O</sub> -DIF	Differential Voltage (differential pins)				1.6	V <sub>ppd</sub>
V <sub>I/O-CM</sub>	Common Mode Voltage (differiential pins)		0		0.8	V
T <sub>A</sub>	Operating temperature range		-40		85	°C

### DC Electrical Characteristics for Switching over Operating Range

Parameters	Description	Test Conditions <sup>(1)</sup>	Min.	Typ.(1)	Max.	Units
V <sub>IH</sub> - SEL	Input HIGH Voltage, SEL Input		2		3.6	
V <sub>IL</sub> - SEL	Input LOW Voltage, SEL Input		0		0.8	V
$v_{IK}$	Clamp Diode Voltage	$V_{\mathrm{DD}} = \mathrm{Max.}$ , $I_{\mathrm{IN}} = -18\mathrm{mA}$		-0.7	-1.2	
IIH	Input HIGH Current, SEL	$V_{DD} = Max., V_{IN} = V_{DD}$			±5	4
IIL	Input LOW Current, SEL	$V_{\mathrm{DD}} = \mathrm{Max.},  V_{\mathrm{IN}} = 0 \mathrm{V}$			±5	μA
I <sub>IN</sub> - SEL	Input Leakage Current, SEL Input	$V_{IN} = V_{IH}$ - SEL Max or $V_{IL}$ - SEL Min	-10		+10	μΑ
IIH	Input HIGH Current, A <sub>X</sub> , B <sub>X</sub> , C <sub>X</sub>	$V_{\mathrm{DD}} = \mathrm{Max.},  V_{\mathrm{IN}} = 1.5 \mathrm{V}$	-10		+10	4
$I_{IL}$	Input LOW Current, A <sub>X</sub> , B <sub>X</sub> , C <sub>X</sub>	$V_{\mathrm{DD}} = \mathrm{Max.},  V_{\mathrm{IN}} = 0 \mathrm{V}$	-10		+10	μΑ
IOZH	HighZ HIGH Current, B <sub>X</sub> , C <sub>X</sub>	$V_{DD} = Max., V_{IN} = 1.5V$	-10		+10	μΑ
IOZL	HighZ LOW Current, B <sub>X</sub> , C <sub>X</sub>	$V_{\mathrm{DD}} = \mathrm{Max.},  V_{\mathrm{IN}} = 0 \mathrm{V}$	-10		+10	μΑ
C <sub>I/O-ON</sub>	ON state I/O capacitance			1.5		pF
RON	ON state resistance	$V_{\rm DD} = 3.3 \text{V},  \mathrm{IO} = 8 \text{mA},  V_{\rm IN} = 0.8 \text{V}$		5		Ω

#### Note:

<sup>1.</sup> Typical values are at  $V_{DD} = 3.3V$ ,  $T_A = 25$ °C ambient and maximum loading.





## **Switching Characteristics**

Parameters	Description	<b>Test Conditions</b>	Min.	Тур.	Max.	Units
tpZH, tpZL	Line Enable Time - SEL to A <sub>N</sub> , B <sub>N</sub> , C <sub>N</sub>		2	20	25	
tpHZ, tPLZ	Line Disable Time - SEL to A <sub>N</sub> , B <sub>N</sub> , C <sub>N</sub> 0.5		0.5	5	25	ns
t <sub>b-b</sub>	Bit-to-bit skew within the same differential pair			5	10	ps
tch-ch	Channel-to-channel skew				20	ps

## **Dynamic Electrical Characteristics**

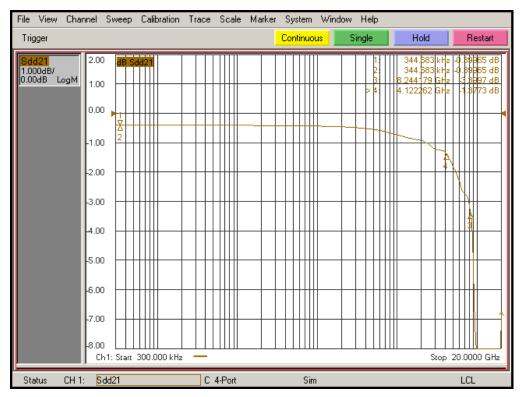
Parameter	Description	<b>Test Conditions</b>	Min.	Typ.(1)	Max.	Units
		f= 50MHz - 1.25GHz		-0.8	-1	
DDII	Differential Insertion Loss	f=1.25GHz - 2.5GHz		-1.0	-1.2	dB
DDIL	$(V_{IN} = -10 dBm, DC = 0V)$	f=2.5GHz - 4GHz		-1.3	-1.6	
		f=5GHz		-1.8	-2.2	
		f= 50MHz - 1.25GHz	-26.3	-32.9		
DDII	Differential Off Isolation	f=1.25GHz - 2.5GHz	-21.4	-26.7		dB
DDIL <sub>OFF</sub>	Differential Off Isolation	f=2.5GHz - 4GHz	-17.6	-22		ив
		f=5GHz	-16	-20		
	Differential Return Loss	f= 50MHz - 1.25GHz	-20	-25		dB
DDRL		f=1.25GHz - 2.5GHz	-18.4	-23		
DDKL		f=2.5GHz - 4GHz	-16.8	-21		
		f=5GHz	-9.6	-12		
		f= 50MHz - 1.25GHz	-34.1	-42.6		dB
DDNEXT	Near End Crosstalk	f=1.25GHz - 2.5GHz	-30.5	-38.1		
DDNEXT	Near End Crosstark	f=2.5GHz - 4GHz	-28.1	-35.1		
		f=5GHz	-27.2	-34		
		Insertion loss 1.5dB, V <sub>IN</sub> =0.623Vpp, DC=0V		4.0		
$V_{IF}$		Insertion loss 1.5dB, V <sub>IN</sub> =0.623Vpp, DC=0.9V		4.0		CIL
	Max Signal Frequency Range	Insertion loss 3dB, V <sub>IN</sub> =0.623Vpp, DC=0V		8.0		GHz
		Insertion loss 3dB, V <sub>IN</sub> =0.623Vpp, DC=0.9V		8.0		
BW	-3dB Bandwidth			8.2		GHz

#### Notes:

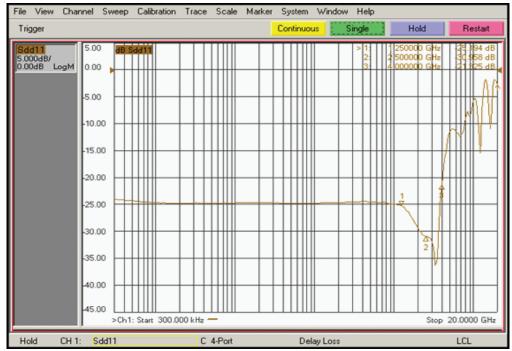
1. Guaranteed by design. Typical values are at  $V_{DD} = 3.3 \text{V}$ ,  $T_A = 25^{\circ}\text{C}$  ambient and maximum loading.







**Differential Insertion Loss** 

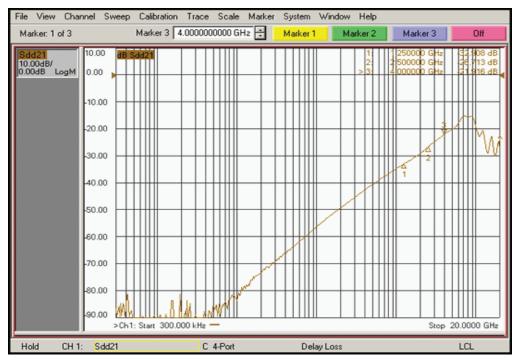


**Differential Return Loss** 

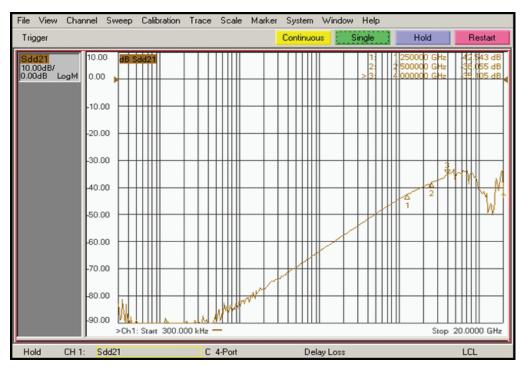
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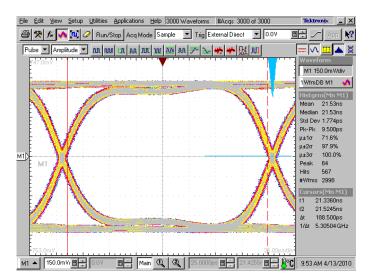
**Differential Off Isolation** 



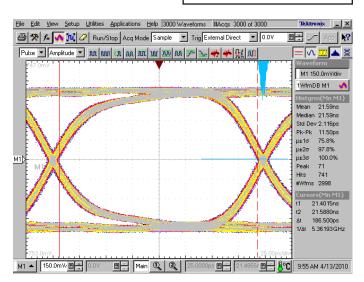
**Differential Crosstalk** 



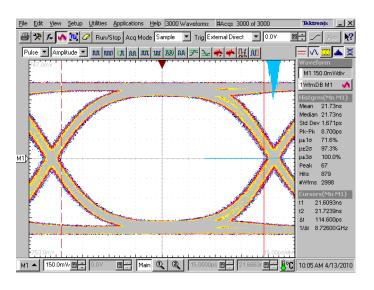




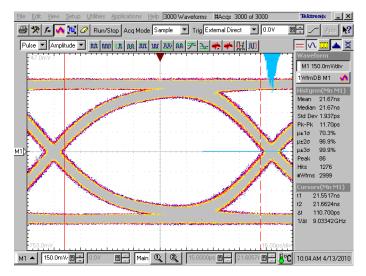
5.0 Gbps RX signal eye without PI3PCIE3412A



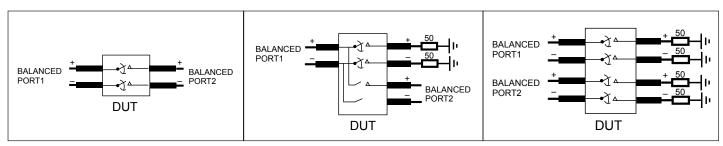
5.0 Gbps RX signal eye with PI3PCIE3412A



8.0 Gbps RX signal eye without PI3PCIE3412A



8.0 Gbps RX signal eye with PI3PCIE3412A



Diff. Insertion Loss and Return Test Circuit

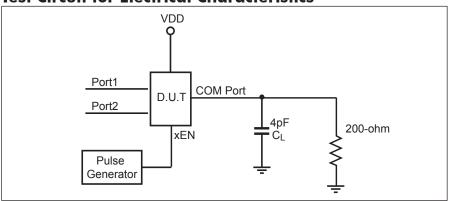
**Diff. Off Isolation Test Circuit** 

Diff. Near End Xtalk Test Circuit





## Test Circuit for Electrical Characteristics $^{(1-5)}$



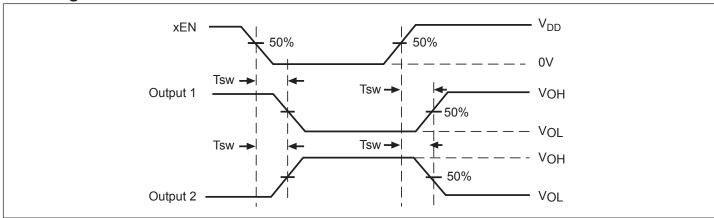
#### Notes

- 1.  $C_L = Load$  capacitance: includes jig and probe capacitance.
- 2.  $R_T$  = Termination resistance: should be equal to  $Z_{OUT}$  of the Pulse Generator
- 3. Output 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Output 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- 4. All input impulses are supplied by generators having the following characteristics:  $PRR \le MHz$ ,  $Z_O = 50\Omega$ ,  $t_R \le 2.5 ns$ ,  $t_F \le 2.5 ns$ .
- 5. The outputs are measured one at a time with one transition per measurement.

### **Switch Positions**

Test	Switch
t <sub>PLZ</sub> , t <sub>PZL</sub>	3.0V
t <sub>PHZ</sub> , t <sub>PZH</sub>	GND
Prop Delay	Open

### **Switching Waveforms**

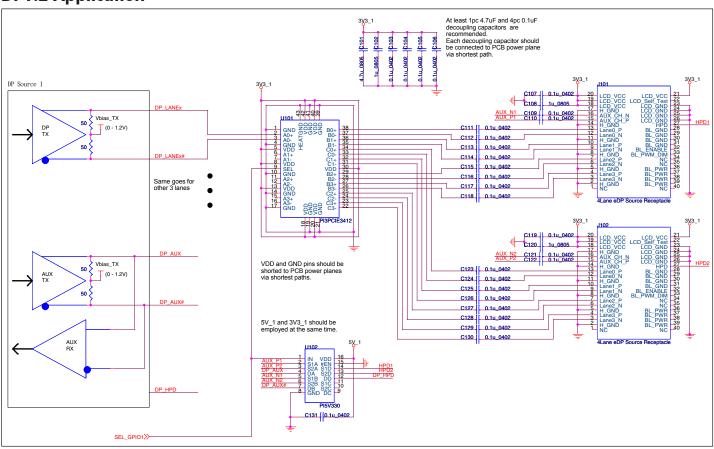


**Voltage Waveforms Enable and Disable Times** 





## **DP1.2 Application**



### **Part Marking Information**

### **ZH Package**

PI3PCIE 3412AZHE O YYWWXX

Y : Year

W : Workweek

1st X: Assembly Code

2nd X: Fab Code

### **ZL Package**

PI3PCIE 3412AZLE O YYWWXX

Y: Year

W : Workweek

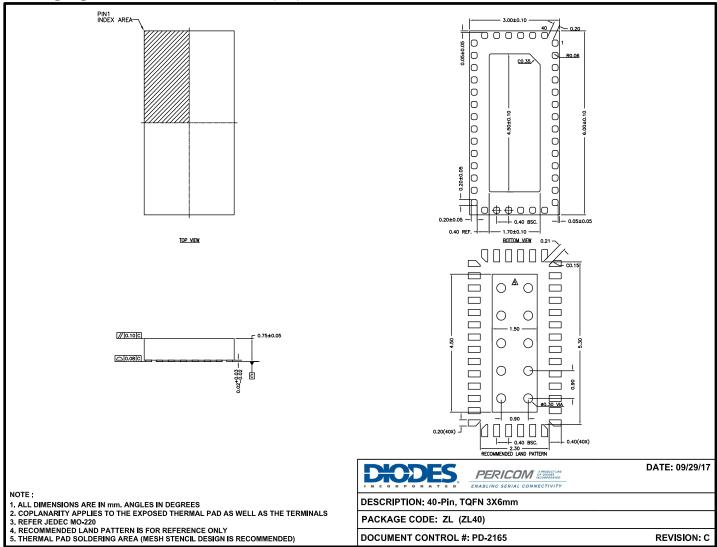
1st X: Assembly Code

2nd X: Fab Code





## Packaging Mechanical: 40-TQFN (ZL)

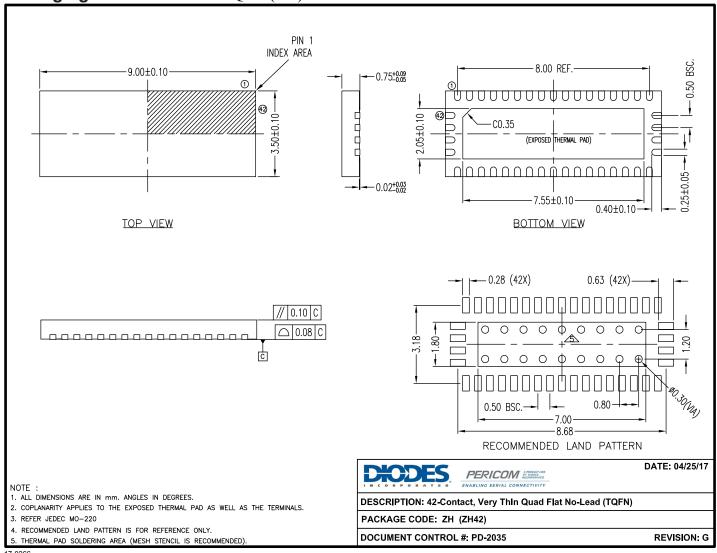


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## Packaging Mechanical: 42-TQFN (ZH)



#### For latest package info.

please check: http://www.diodes.com/design/support/packaging/pericom-packaging/packaging-mechanicals-and-thermal-characteristics/

### **Ordering Information**

Ordering Code	Package Code	Package Description
PI3PCIE3412AZLEX	ZL	40-pin, 3x6mm(TQFN)
PI3PCIE3412AZHEX	ZH	42-contact, Very Thin Quad Flat No-Lead (TQFN)

#### Notes:

- Thermal characteristics can be found on the company web site at www.diodes.com/design/support/packaging/
- E = Pb-free and Green
- X suffix = Tape/Reel





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